

Application No.: 10/826,261**Docket No.: 4459-147****ABSTRACT**

A micromachine package ~~comprises~~ includes a first chip, a second chip, a spacer ring, a plurality of bumps, a plurality of leads, and an encapsulant. The first chip has at least one moveable structure. The second chip has at least one electrode for cooperating with the moveable structure of the first chip, and a plurality of pads disposed on one side of the second chip. The spacer ring is disposed between the first chip and the opposite second chip and surrounds the moveable structure. The bumps are disposed on the pads. The lead has a first surface, which is connected to the bumps, and an opposite second surface. The encapsulant encapsulates the first chip, the second chip, the spacer ring, the bumps, and the first surfaces of the leads, and the second surfaces of the leads are exposed out of the encapsulant.